



**THE DATASHEET OF  
IPLU300N04S4R8XTMA1**



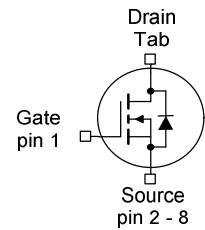
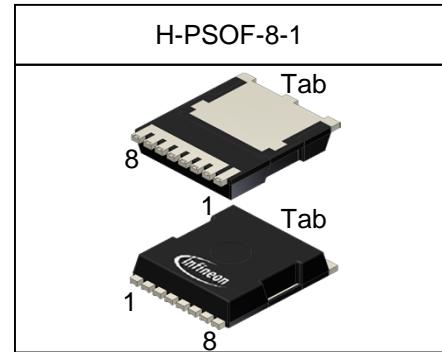
**OptiMOS™-T2 Power-Transistor**

**Features**

- N-channel - Enhancement mode
- AEC qualified
- MSL1 up to 260°C peak reflow
- 175°C operating temperature
- Green product (RoHS compliant); 100% lead free
- Ultra low Rds(on)
- 100% Avalanche tested

**Product Summary**

|              |      |    |
|--------------|------|----|
| $V_{DS}$     | 40   | V  |
| $R_{DS(on)}$ | 0.77 | mΩ |
| $I_D$        | 300  | A  |



| Type            | Package    | Marking |
|-----------------|------------|---------|
| IPLU300N04S4-R8 | H-PSOF-8-1 | 4N04R8  |

**Maximum ratings, at  $T_j=25\text{ °C}$ , unless otherwise specified**

| Parameter                                    | Symbol         | Conditions  | Value        | Unit |
|--|----------------|---|--------------|------|
| Continuous drain current                     | $I_D$          | $T_C=25\text{ °C}$ , $V_{GS}=10\text{V}^{1)}$     | 300          | A    |
|  |                | $T_C=100\text{ °C}$ ,<br>$V_{GS}=10\text{V}^{2)}$ | 300          |      |
| Pulsed drain current <sup>2)</sup>           | $I_{D,pulse}$  | $T_C=25\text{ °C}$                                | 1200         |      |
| Avalanche energy, single pulse <sup>2)</sup> | $E_{AS}$       | $I_D=150\text{ A}$                                | 750          | mJ   |
| Avalanche current, single pulse              | $I_{AS}$       | -   | 300          | A    |
| Gate source voltage                          | $V_{GS}$       | -   | ±20          | V    |
| Power dissipation                            | $P_{tot}$      | $T_C=25\text{ °C}$                                | 429          | W    |
| Operating and storage temperature            | $T_j, T_{stg}$ | -   | -55 ... +175 | °C   |

| Parameter | Symbol | Conditions | Values |      |      | Unit |
|-----------|--------|------------|--------|------|------|------|
|           |        |            | min.   | typ. | max. |      |

**Thermal characteristics<sup>2)</sup>**

|                                     |            |  |   |   |      |     |
|-------------------------------------|------------|--|---|---|------|-----|
| Thermal resistance, junction - case | $R_{thJC}$ | -  | - | - | 0.35 | K/W |
| SMD version, device on PCB          | $R_{thJA}$ | minimal footprint                            | - | - | 62   |     |
|                                     |            | 6 cm <sup>2</sup> cooling area <sup>3)</sup> | - | - | 40   |     |

**Electrical characteristics, at  $T_j=25\text{ °C}$ , unless otherwise specified**
**Static characteristics**

|                                  |               |   |     |      |      |               |
|----------------------------------|---------------|---|-----|------|------|---------------|
| Drain-source breakdown voltage   | $V_{(BR)DSS}$ | $V_{GS}=0\text{ V}$ ,<br>$I_D=1\text{ mA}$                              | 40  | -    | -    | V             |
| Gate threshold voltage           | $V_{GS(th)}$  | $V_{DS}=V_{GS}$ , $I_D=230\text{ }\mu\text{A}$                          | 2.0 | 3.0  | 4.0  |               |
| Zero gate voltage drain current  | $I_{DSS}$     | $V_{DS}=40\text{ V}$ , $V_{GS}=0\text{ V}$ ,<br>$T_j=25\text{ °C}$      | -   | 0.1  | 10   | $\mu\text{A}$ |
|                                  |               | $V_{DS}=18\text{ V}$ , $V_{GS}=0\text{ V}$ ,<br>$T_j=85\text{ °C}^{2)}$ | -   | 1    | 20   |               |
| Gate-source leakage current      | $I_{GSS}$     | $V_{GS}=20\text{ V}$ , $V_{DS}=0\text{ V}$                              | -   | -    | 100  | nA            |
| Drain-source on-state resistance | $R_{DS(on)}$  | $V_{GS}=10\text{ V}$ , $I_D=100\text{ A}$                               | -   | 0.53 | 0.77 | m $\Omega$    |

| Parameter | Symbol | Conditions | Values |      |      | Unit |
|-----------|--------|------------|--------|------|------|------|
|           |        |            | min.   | typ. | max. |      |

**Dynamic characteristics<sup>2)</sup>**

|                              |              |  |   |       |       |    |
|------------------------------|--------------|--|---|-------|-------|----|
| Input capacitance            | $C_{iss}$    | $V_{GS}=0\text{ V}, V_{DS}=25\text{ V},$<br>$f=1\text{ MHz}$                     | - | 17650 | 22945 | pF |
| Output capacitance           | $C_{oss}$    |  | - | 3790  | 4930  |    |
| Reverse transfer capacitance | $C_{rss}$    |  | - | 130   | 300   |    |
| Turn-on delay time           | $t_{d(on)}$  | $V_{DD}=20\text{ V}, V_{GS}=10\text{ V},$<br>$I_D=300\text{ A}, R_G=3.5\ \Omega$ | - | 50    | -     | ns |
| Rise time                    | $t_r$        |  | - | 22    | -     |    |
| Turn-off delay time          | $t_{d(off)}$ |  | - | 68    | -     |    |
| Fall time                    | $t_f$        |  | - | 61    | -     |    |

**Gate Charge Characteristics<sup>2)</sup>**

|                       |               |   |   |     |     |    |
|-----------------------|---------------|---|---|-----|-----|----|
| Gate to source charge | $Q_{gs}$      | $V_{DD}=32\text{ V}, I_D=300\text{ A},$<br>$V_{GS}=0\text{ to }10\text{ V}$ | - | 90  | 130 | nC |
| Gate to drain charge  | $Q_{gd}$      |   | - | 27  | 68  |    |
| Gate charge total     | $Q_g$         |   | - | 221 | 287 |    |
| Gate plateau voltage  | $V_{plateau}$ |   | - | 5.1 | -   | V  |

**Reverse Diode**

|  |               |   |   |     |      |    |
|--|---------------|---|---|-----|------|----|
| Diode continuous forward current <sup>2)</sup> | $I_S$         | $T_C=25\text{ }^\circ\text{C}$  | - | -   | 300  | A  |
| Diode pulse current <sup>2)</sup>              | $I_{S,pulse}$ |   | - | -   | 1200 |    |
| Diode forward voltage                          | $V_{SD}$      | $V_{GS}=0\text{ V}, I_F=100\text{ A},$<br>$T_j=25\text{ }^\circ\text{C}$  | - | 0.9 | 1.3  | V  |
| Reverse recovery time <sup>2)</sup>            | $t_{rr}$      | $V_R=20\text{ V}, I_F=50\text{ A},$<br>$di_F/dt=100\text{ A}/\mu\text{s}$ | - | 85  | -    | ns |
| Reverse recovery charge <sup>2)</sup>          | $Q_{rr}$      |   | - | 132 | -    | nC |

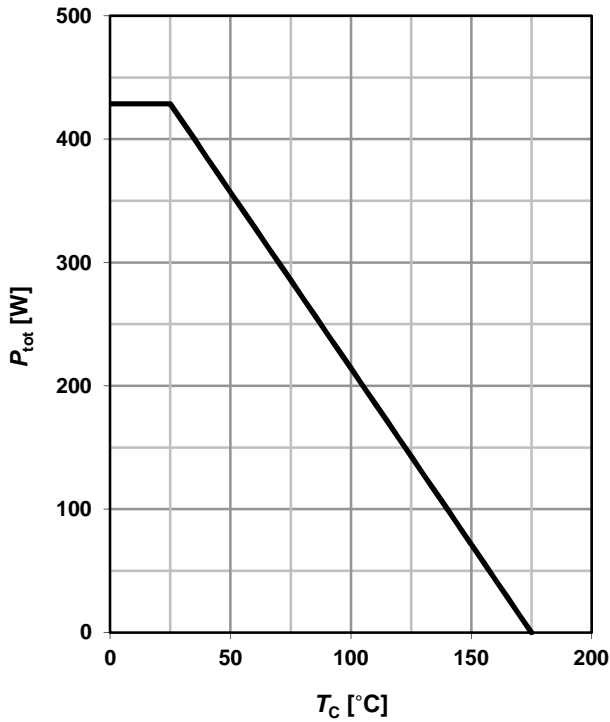
<sup>1)</sup> Current is limited by bondwire; with an  $R_{thJC} = 0.35\text{ K/W}$  the chip is able to carry 697A at 25°C.

<sup>2)</sup> Defined by design. Not subject to production test.

<sup>3)</sup> Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm<sup>2</sup> (one layer, 70 μm thick) copper area for drain connection. PCB is vertical in still air.

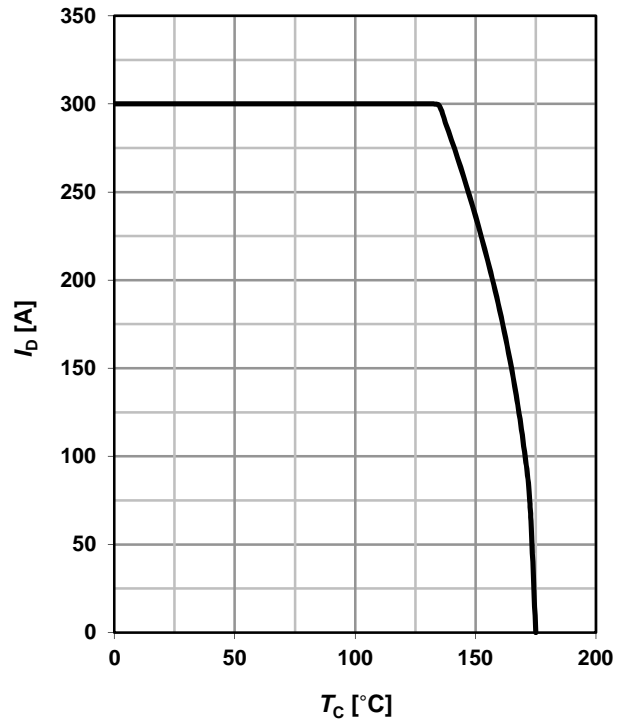
**1 Power dissipation**

$P_{tot} = f(T_C); V_{GS} = 10\text{ V}$



**2 Drain current**

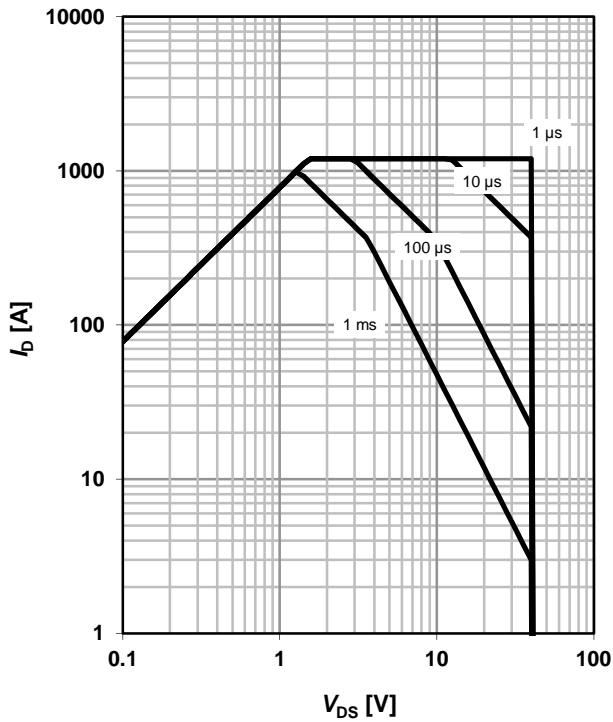
$I_D = f(T_C); V_{GS} = 10\text{ V}$



**3 Safe operating area**

$I_D = f(V_{DS}); T_C = 25\text{ °C}; D = 0$

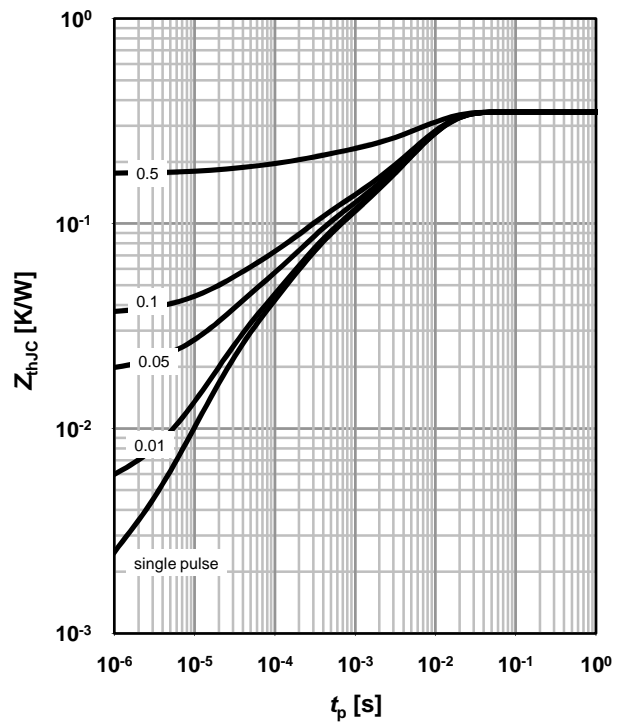
parameter:  $t_p$



**4 Max. transient thermal impedance**

$Z_{thJC} = f(t_p)$

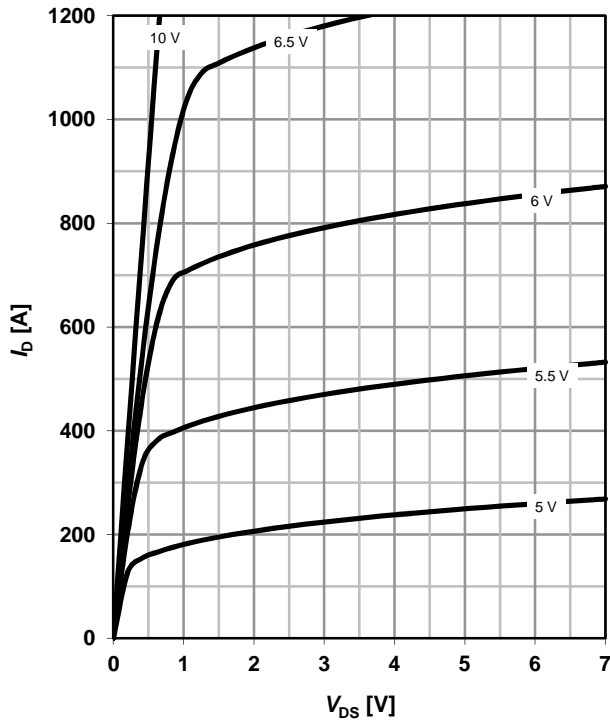
parameter:  $D = t_p/T$



**5 Typ. output characteristics**

$I_D = f(V_{DS}); T_j = 25\text{ °C}$

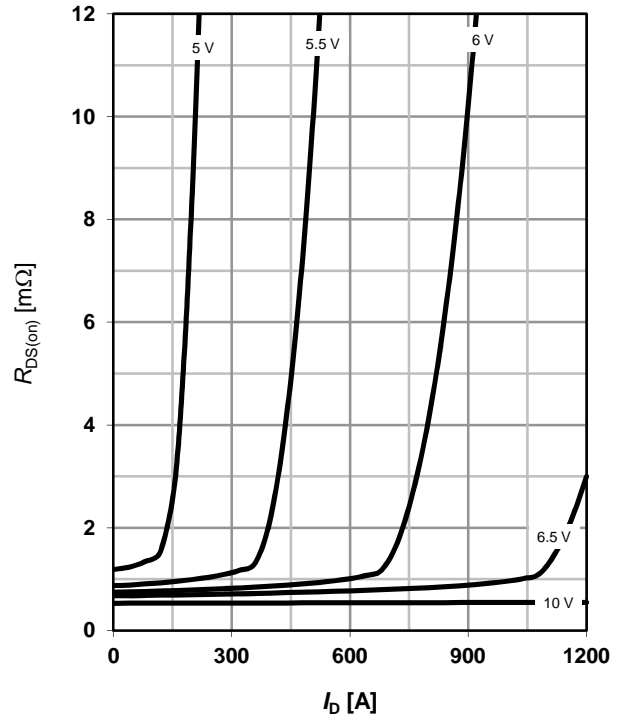
parameter:  $V_{GS}$



**6 Typ. drain-source on-state resistance**

$R_{DS(on)} = f(I_D); T_j = 25\text{ °C}$

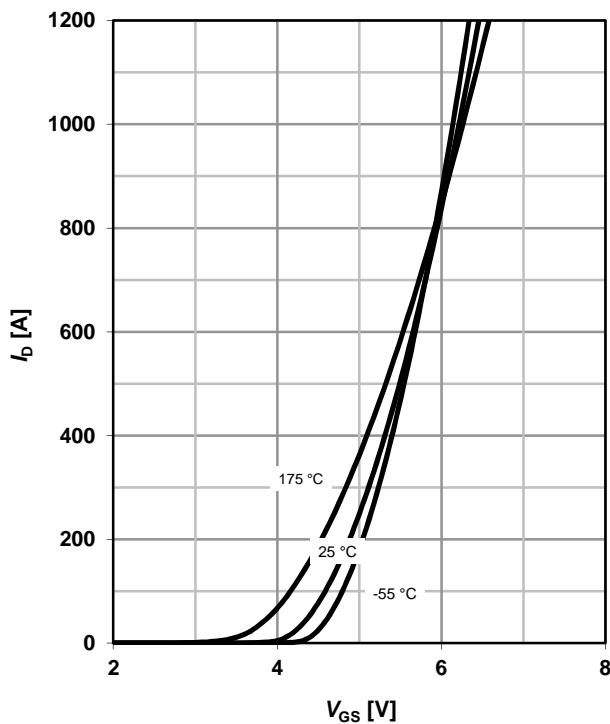
parameter:  $V_{GS}$



**7 Typ. transfer characteristics**

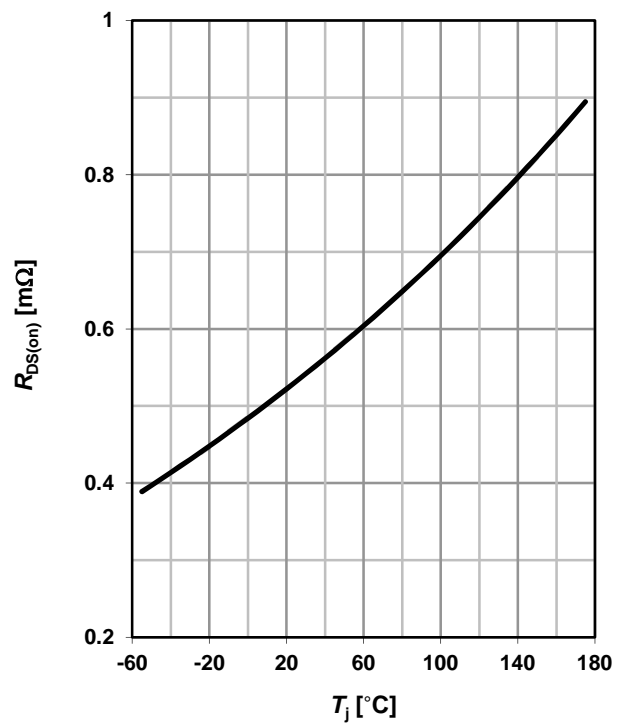
$I_D = f(V_{GS}); V_{DS} = 6\text{ V}$

parameter:  $T_j$



**8 Typ. drain-source on-state resistance**

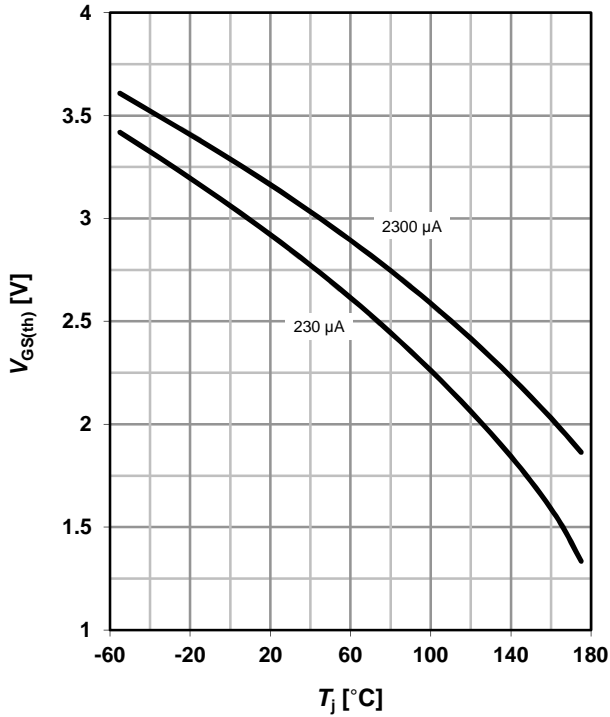
$R_{DS(on)} = f(T_j); I_D = 100\text{ A}; V_{GS} = 10\text{ V}$



**9 Typ. gate threshold voltage**

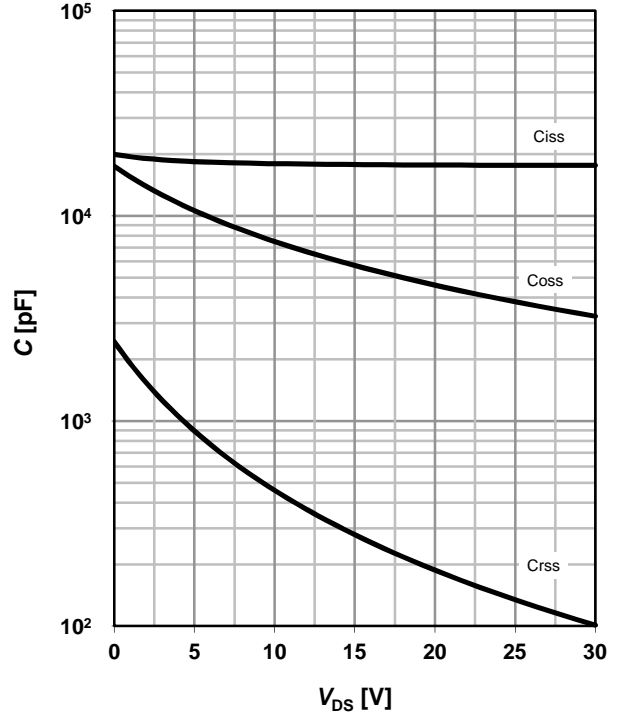
$V_{GS(th)} = f(T_j); V_{GS} = V_{DS}$

parameter:  $I_D$



**10 Typ. capacitances**

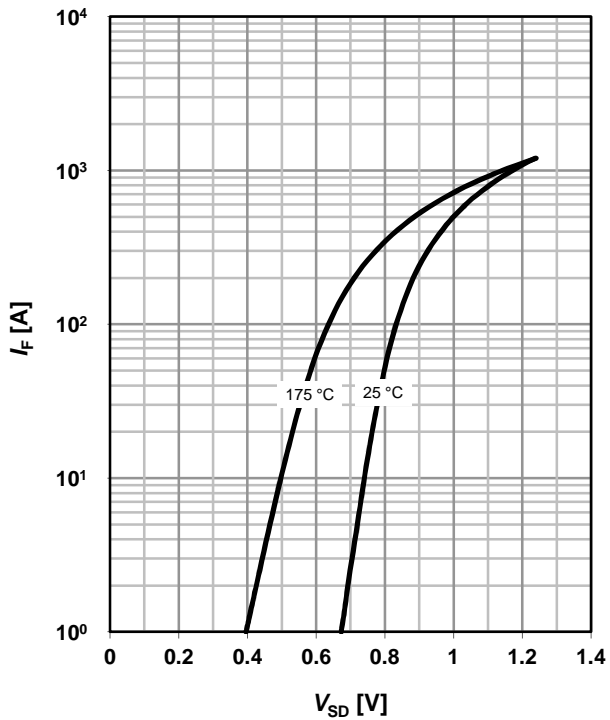
$C = f(V_{DS}); V_{GS} = 0 V; f = 1 MHz$



**11 Typical forward diode characteristics**

$I_F = f(V_{SD})$

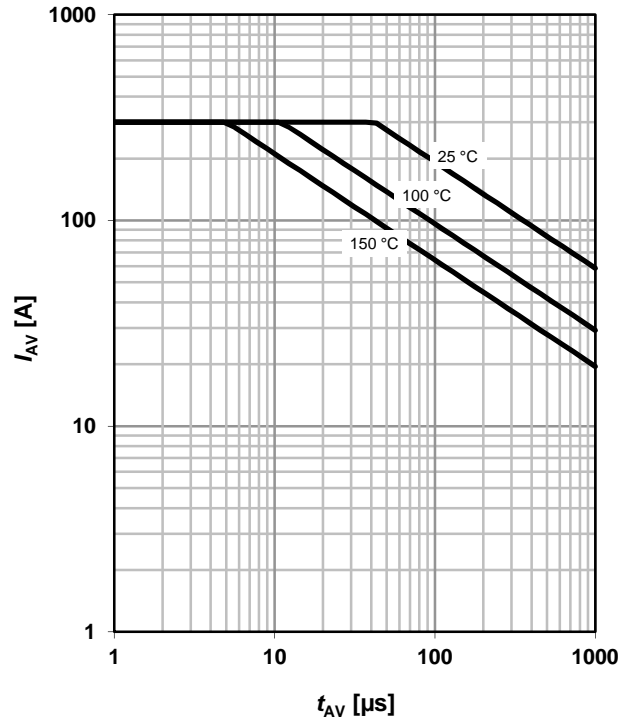
parameter:  $T_j$



**12 Avalanche characteristics**

$I_{AS} = f(t_{AV})$

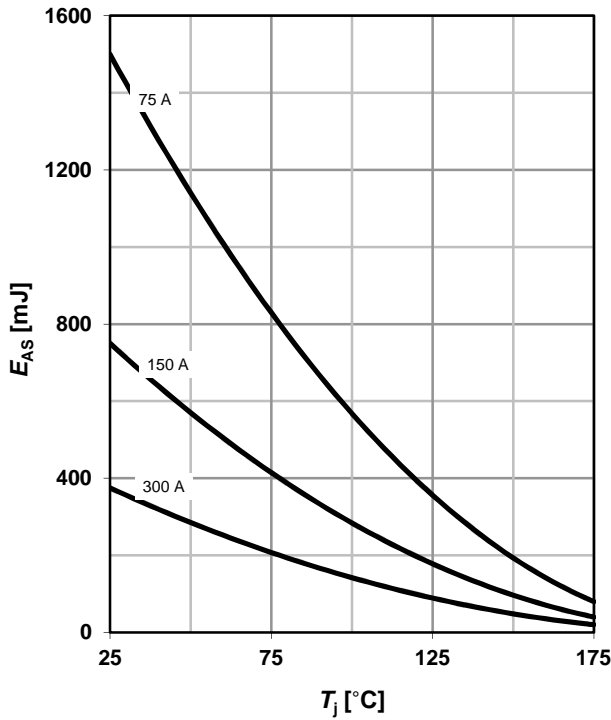
parameter:  $T_{j(start)}$



**13 Avalanche energy**

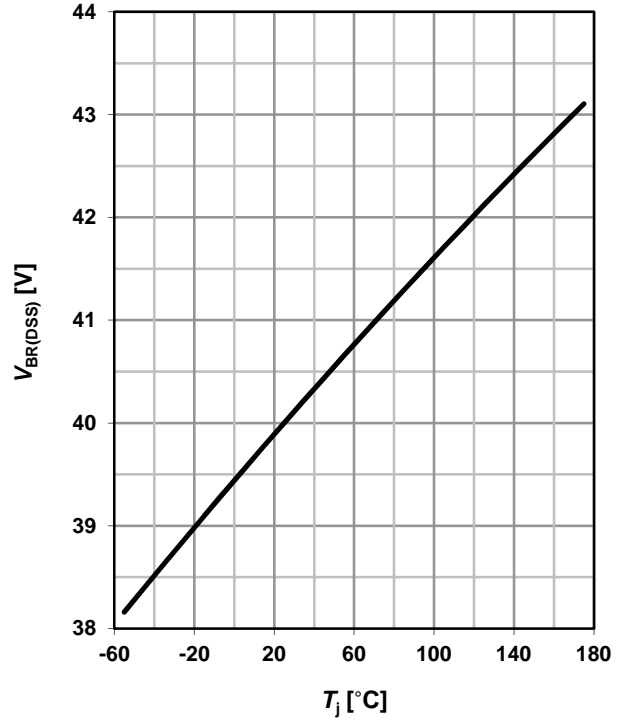
$$E_{AS} = f(T_j)$$

parameter:  $I_D$



**14 Drain-source breakdown voltage**

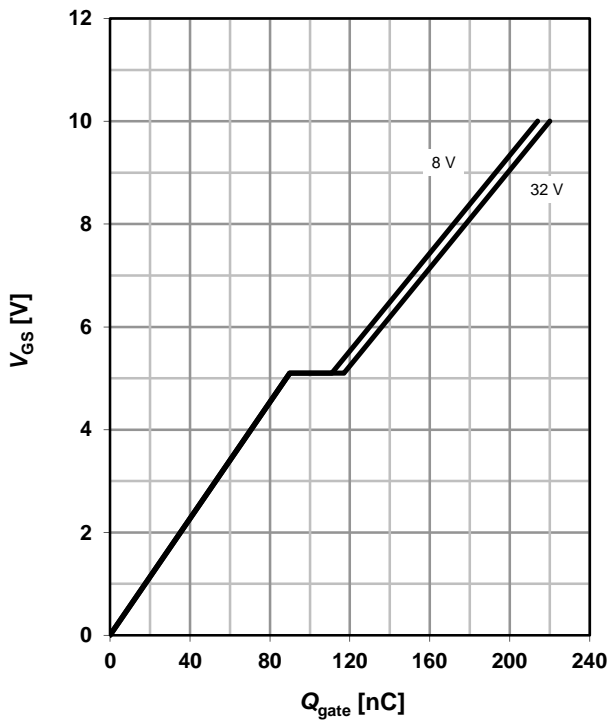
$$V_{BR(DSS)} = f(T_j); I_D = 1 \text{ mA}$$



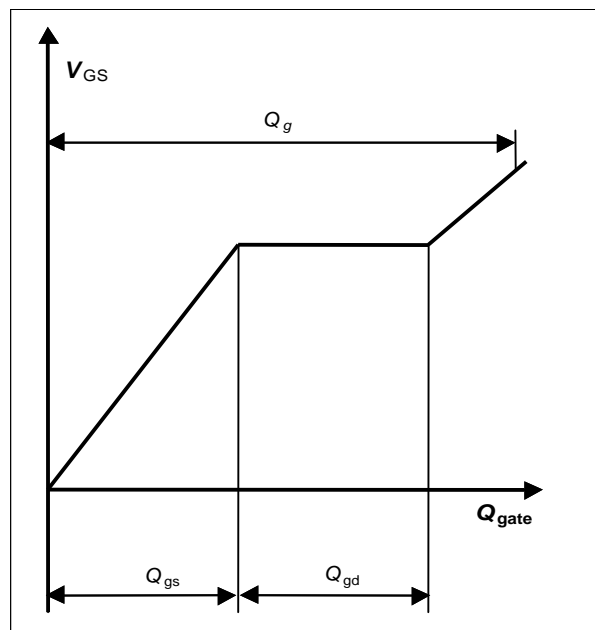
**15 Typ. gate charge**

$$V_{GS} = f(Q_{gate}); I_D = 300 \text{ A pulsed}$$

parameter:  $V_{DD}$



**16 Gate charge waveforms**



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## Revision History

| Version      | Date       | Changes               |
|--------------|------------|-----------------------|
| Revision 1.0 | 2014-08-12 | Final Data Sheet      |
| Revision 1.1 | 2015-10-05 | Update of gate charge |

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